

TSMC-03-336



January 22, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/718,192 11/20/03 |

Yian-Liang Kuo et al.

A HEAT SPREADER BALL GRID ARRAY
(HSBGA) DESIGN FOR LOW-K INTEGRATED
CIRCUITS (IC)

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

A handwritten signature of "SBA" followed by the date "1/27/04".

TSMC-03-336

U.S. Patent 5,977,633 to Suzuki et al., "Semiconductor Device with Metal Base Substrate Having Hollows," describes a semiconductor device with metal base substrate having hollows.

U.S. Patent 5,223,741 to Bechtel et al., "Package for an Integrated Circuit Structure," describes a package for an integrated circuit structure.

U.S. Patent 5,585,671 to Nagesh et al., "Reliable Low Thermal Resistance Package for High Power Flip Chip ICs," describes a low thermal resistance package for high power flip chip ICs.

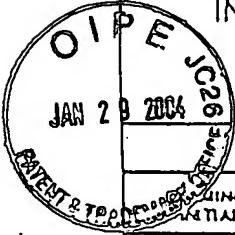
U.S. Patent 6,462,410 to Novotny et al., "Integrated Circuit Component Temperature Gradient Reducer," describes an integrated circuit component temperature gradient reducer.

U.S. Patent 4,748,495 to Kucharek, "High Density Multi-Chip Interconnection and Cooling Package," describes a high density multi-chip interconnection and cooling package.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761



**INFORMATION DISCLOSURE CITATION
IN AN APPLICATION**

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(Use several sheets if necessary)

Doctor Number (Optional)

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10/718, 192

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Yian-Liang Kuo et al.

Filing Dates

11 / 20 / 03

11/20/03

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.



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ASSOCIATE POWER OF ATTORNEY

I hereby appoint Stephen G. Stanton, registration number 35,690, as my associate attorney in this case. His telephone number is (610) 296-5194.

Please continue to direct all correspondence in this case to the undersigned attorney.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "SBA".

Stephen B. Ackerman,

Principal attorney of record